

MECHANICAL CASE OUTLINE

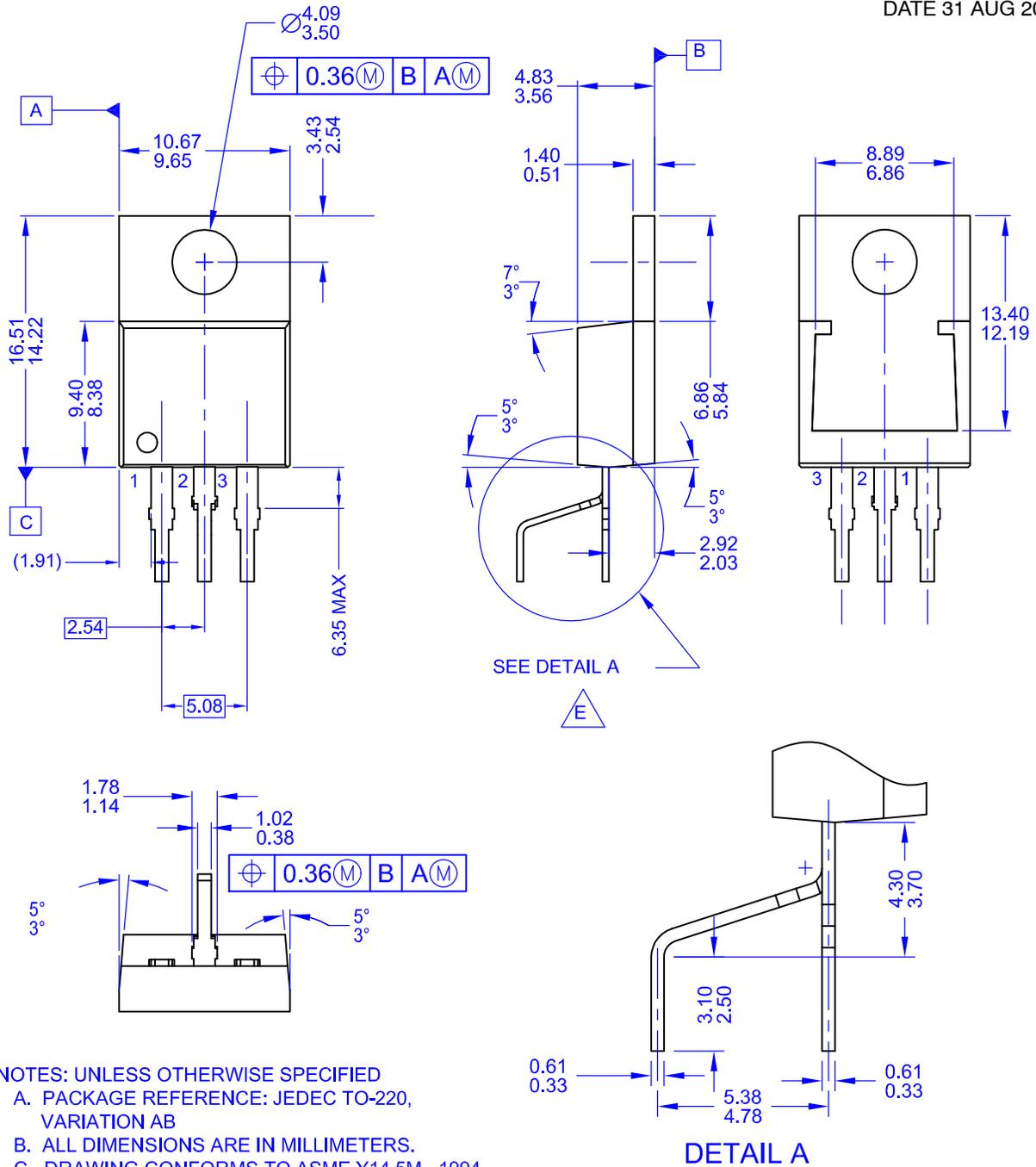
PACKAGE DIMENSIONS

ON Semiconductor®



TO-220-3LD
CASE 340AX
ISSUE O

DATE 31 AUG 2016



- NOTES: UNLESS OTHERWISE SPECIFIED
- A. PACKAGE REFERENCE: JEDEC TO-220, VARIATION AB
 - B. ALL DIMENSIONS ARE IN MILLIMETERS.
 - C. DRAWING CONFORMS TO ASME Y14.5M - 1994
 - D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
 - E. DOES NOT COMPLY TO JEDEC STANDARD VALUE

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